TENTATIVE

TOSHIBA Bi-CMOS Integrated Circuit Silicon Monolithic

TB62778FNG

8-Channel Constant-Current LED Driver of the 3.3-V and 5-V Power Supply Voltage Operation

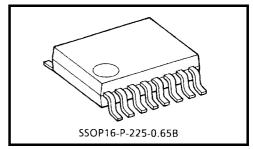
The TB62778FNG is comprised of constant-current drivers designed for LEDs and LED panel displays.

The regulated current sources are designed to provide a constant current, which is adjustable through one external resistor.

The TB62778FNG incorporates eight channels of shift registers, latches, AND gates and constant-current outputs.

Fabricated using the Bi-CMOS process, the TB62778FNG satisfies the system requirement of high-speed data transmission.

The TB62778FNG is RoHS.



Weight: 0.07 g (typ.)

Features

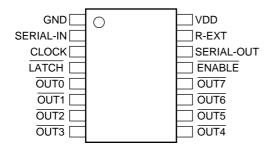
- Power supply voltages: $V_{DD} = 3.3 \text{ V/5 V}$
- Output drive capability and output count: 50 mA \times 8 channels
- Constant-current output range: 5 to 40 mA
- Voltage applied to constant-current output terminals: 0.4 V (I_{OUT} = 5 to 40 mA)
- Current adjustment (via 7-bit serial data): The MSB, or the HC bit, selects the output current range: 25% to 50% range when HC = 0 or 50% to 100% range when HC = 1 The six LSB bits are used to adjust the current in 64 steps within the selected range.
- Designed for common-anode LEDs
- Thermal shutdown (TSD)
- Power on reset (POR)
- Output-open detection (OOD) and output-short detection (OSD)
- Input signal voltage level: 3.3-V and 5-V CMOS interfaces (Schmitt trigger input)
- Maximum output voltage: 25V
- Serial data transfer rate: 25 MHz (max) @cascade connection
- Operating temperature range: $T_{opr} = -40$ to $85^{\circ}C$
- Package: SSOP-P-225-0.65B
- Constant-current accuracy

Output Voltage	Current accuracy Between Channels	Current Accuracy Between ICs	Output Current	
0.4 V to 4 V ±3%		±6%	15 mA	

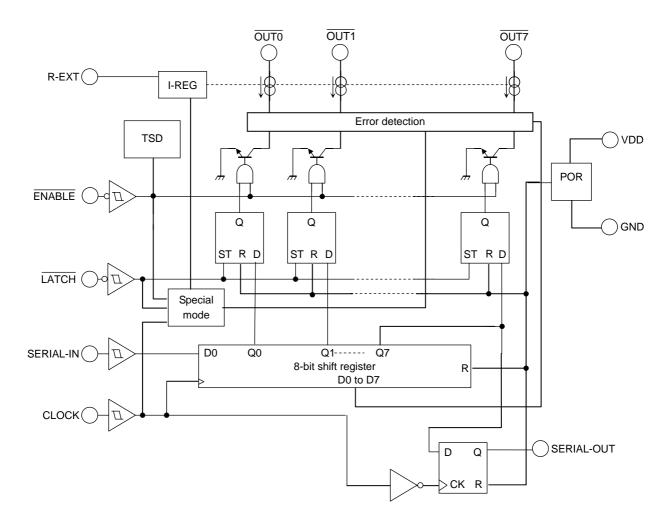


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Pin Assignment (top view)



Block Diagram



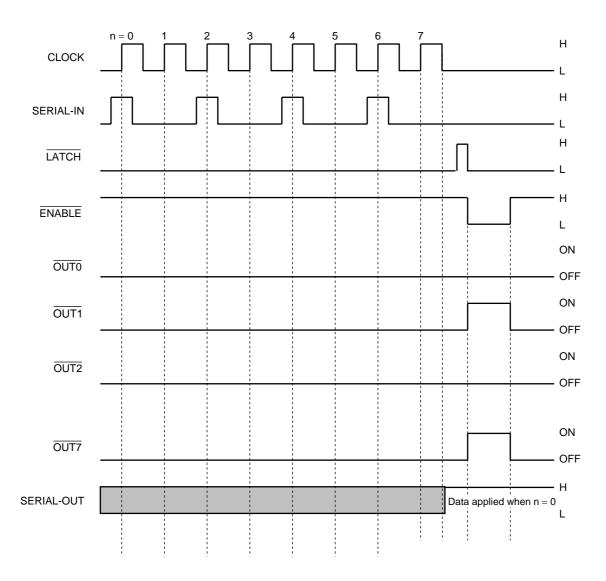
Truth Table

CLOCK	LATCH	ENABLE	SERIAL-IN	OUTO OUT5 OUT7	SERIAL-OUT
	Н	L	Dn	Dn Dn – 5 Dn – 7	No change
	L	L	Dn + 1	No Change	No change
	Н	L	Dn + 2	Dn + 2 Dn - 3 Dn - 5	No change
	Х	Н	Dn + 3	OFF	No change
\square	Х	Н	Dn + 3	OFF	Dn - 4

Note 1: \overline{OUTO} to $\overline{OUT7}$ = On when Dn = H; \overline{OUTO} to $\overline{OUT7}$ = Off when Dn = L.

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Timing Diagram



Note 1: Latches are level-sensitive, not edge-triggered.

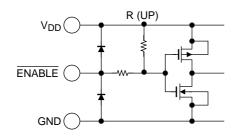
- Note 2: The TB62778FNG can be used at 3.3 V or 5.0 V. However, the V_{DD} supply voltage must be equal to the input voltage.
- Note 3: Serial data is shifted out of SERIAL-OUT on the falling edge of CLOCK.
- Note 4: The latches hold data while the LATCH terminal is held Low. When the LATCH terminal is High, the latches do not hold data and pass it transparently. When the ENABLE terminal is Low, OUTO to OUT7 toggle between ON and OFF according to the data. When the ENABLE terminal is High, OUT0 to OUT7 are forced OFF.

Terminal Description

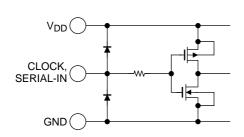
Pin No.	Pin Name	Function
1	GND	GND terminal
2	SERIAL-IN	Serial data input terminal
3	CLOCK	Serial clock input terminal
4	LATCH	Latch input terminal
5	OUT0	Constant-current output terminal
6	OUT1	Constant-current output terminal
7	OUT2	Constant-current output terminal
8	OUT3	Constant-current output terminal
9	OUT4	Constant-current output terminal
10	OUT5	Constant-current output terminal
11	OUT6	Constant-current output terminal
12	OUT7	Constant-current output terminal
13	ENABLE	Output enable input terminal All outputs (\overline{OUTO} to $\overline{OUT7}$) are disabled when the \overline{ENABLE} terminal is driven High, and enabled when it is driven Low.
14	SERIAL-OUT	Serial data output terminal. Serial data is clocked out on the falling edge of CLOCK.
15	R-EXT	An external resistor is connected between this terminal and ground. $\overline{OUT0}$ to $\overline{OUT7}$ are adjusted to the same current value.
16	V _{DD}	Power supply terminal

Equivalent Circuits for Inputs and Outputs

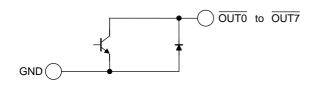
1. ENABLE Terminal



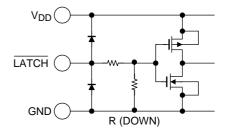
3. CLOCK and SERIAL-IN Terminals



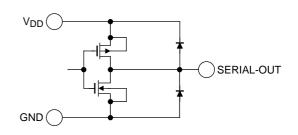
5. $\overline{\text{OUT0}}$ to $\overline{\text{OUT7}}$ Terminals



2. LATCH Terminal



4. SERIAL-OUT Terminal



Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Supply voltage	V _{DD}	6.0	V
Input voltage	VIN	-0.3 to V _{DD} + 0.3 (Note 1)	V
Output current	IOUT	55	mA/ch
Output voltage	V _{OUT}	0.3 to 25	V
Power dissipation	Pd	1.02 (Notes 2 and 3)	W
Thermal resistance	R _{th (j-a)}	122 (Note 2)	°C/W
Operating temperature range	T _{opr}	-40 to 85	°C
Storage temperature range	T _{stg}	-55 to 150	°C
Maximum junction temperature	Тj	150	°C

Note 1: However, do not exceed 6.0 V.

Note 2: When mounted on a PCB ($76.2 \times 114.3 \times 1.6$ mm; Cu = 30%; 35-µm-thick; SEMI-compliant)

Note 3: Power dissipation is reduced by 1/Rth (j-a) for each °C above 25°C ambient.

Operating Ranges (unless otherwise specified, Ta = -40^{\circ}C to 85^{\circ}C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Supply voltage	V _{DD}	—	3	_	5.5	V
Output voltage	V _{OUT}	OUT0 to OUT7	0.4	_	4	V
	lout	OUT0 to OUT7	5	_	40	mA/ch
Output current	Іон	SERIAL-OUT	_	_	-5	mA
	I _{OL}	SERIAL-OUT	_	_	5	mA
	V _{IH}	SERIAL-IN/CLOCK/	$0.7 \times V_{DD}$	_	V _{DD}	v
Input voltage	VIL	LATCH / ENABLE	GND	_	$0.3 \times V_{DD}$	V
Clock frequency	fclk	Cascade connection	—	_	25	MHz
LATCH pulse width	t _{wLAT}	(Note 2	20	_	_	ns
CLOCK pulse width	t _{wCLK}	(Note 2	20	_	_	115
	t _{wENA}	$I_{OUT} \ge 20 \text{ mA}$ (Note 2	2	—	—	μS
ENABLE pulse width	WENA	$5 \text{ mA} \le I_{OUT} \le 20 \text{ mA}$ (Note 2) 3	—	—	μο
	tSETUP1		5	—	—	
Setup time	tSETUP2		5	—	—	
	tSETUP3		5	—	_	
	tSETUP4	– (Note 2	5	—	_	ns
	tHOLD1		5	_	_	115
Hold time	t _{HOLD2}		5	—	—	
	t _{HOLD3}		10	—	—	
	t _{HOLD4}		10	_	—	
Maximum clock rise time	tr	- Single operation (Notes 1 and 2	_	_	5	
Maximum clock fall time	t _f	- Single operation (Notes 1 and 2		_	5	μS

Note 1: For cascade operation, the CLOCK waveform might become ambiguous, causing the t_r and t_f values to be large. Then it may not be possible to meet the timing requirement for data transfer. Please consider the timing carefully.

Note 2: Please see the timing waveform on page 13.

Electrical Characteristics (Unless otherwise specified, $Ta = 25^{\circ}C$, $V_{DD} = 4.5$ to 5.5 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	I _{OUT1}	5	V_{OUT} = 0.4 V, R-EXT = 1.2 k Ω V_{DD} = 5 V, VG = 1		15		mA
Output current error between ICs	∆lout1	5	V_{OUT} = 0.4 V, R-EXT = 1.2 k Ω All channels ON V_{DD} = 5 V, VG = 1		±3	±6	%
Output current error between channels	ΔI_{OUT2}	5	V_{OUT} = 0.4 V, R-EXT = 1.2 k Ω All channels ON V_{DD} = 5 V, VG = 1		±1	±3	%
Output leakage current	I _{OZ}	5	V _{OUT} = 25 V	_	_	1	μA
Input voltage	VIH	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	0.7 × V _{DD}	_	V _{DD}	V
input voltage	VIL	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	GND	_	0.3 × V _{DD}	v
Input current	Ιн	2	V _{IN} = V _{DD} CLOCK/SERIAL-IN/ ENABLE			1	μA
	١ _{١L}	3	V _{IN} = GND CLOCK/SERIAL-IN/ LATCH			-1	μΑ
SERIAL-OUT output voltage	V _{OL}	1	$I_{OL} = 5.0 \text{ mA}, V_{DD} = 5 \text{ V}$			0.3	V
	V _{OH}	1	I _{OH} = –5.0 mA, V _{DD} = 5 V	4.7	—	—	
OOD detection voltage	VOOD	7	5 to 40 mA	0.2	0.3	0.4	V
OSD detection voltage	V _{OSD}	7	5 to 40 mA	0.9 × V _{DD}	$0.95 \times V_{DD}$	V _{DD}	V
Changes in constant output current dependent on V _{DD}	%/V _{DD}	5	V _{DD} = 3 V to 5.5 V		1	2	%
Pull-up resistor	R _(Up)	3	ENABLE	160	200	240	kΩ
Pull-down resistor	R (Down)	2	LATCH	160	200	240	kΩ
	IDD (OFF) 1	4	R-EXT = OPEN, V _{OUT} = 25.0 V		_	1	
Supply current	I _{DD} (OFF) 2	4	R-EXT = 1.2 kΩ, V _{OUT} = 25.0 V, All channels OFF		_	5	mA
	I _{DD (ON)}	4	$R\text{-}EXT$ = 1.2 k $\Omega,~V_{OUT}$ = 0.4 V, All channels ON	_		9	

Switching Characteristics (Unless otherwise specified, $Ta = 25^{\circ}C$, $V_{DD} = 4.5$ to 5.5V)

Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	t _{pLH1}	6	$ \begin{array}{l} CLK- \overline{OUTn} \;, \;\; \overline{LATCH} = "H", \\ \overline{ENABLE} = "L" \end{array} $	_	20	300	
	t _{pLH2}	6	$\overline{LATCH} = \overline{OUTn} ,$ ENABLE = "L"	_	20	300	
	t _{pLH3}	6	ENABLE – OUTn , LATCH = "H"	_	20	300	
Propagation delay time	t _{pLH}	6	CLK-SERIAL OUT	2	10	14	
Propagation delay time	^t pHL1	6	$ \begin{array}{l} CLK-\overline{OUTn} \ , \ \overline{LATCH} = "H", \\ \overline{ENABLE} = "L" \end{array} $	_	30	340	ns
	t _{pHL2}	6	$\overline{LATCH} = \overline{OUTn},$ ENABLE = "L"	—	70	340	
	t _{pHL3}	6	ENABLE – OUTn , LATCH = "H"	_	70	340	
	t _{pHL}	6	CLK-SERIAL OUT	2	10	14	
Output rise time	t _{or}	6	10% to 90% points of OUT0 to OUT7 voltage waveforms		20	150	
Output fall time	t _{of}	6	6 90% to 10% points of OUT0 to OUT7 voltage waveforms		125	300	

Note 1: $T_{opr} = 25^{\circ}C$, $V_{DD} = V_{IH} = 5$ V, $V_{IL} = 0$ V, $R_{EXT} = 1.2 \text{ k}\Omega$, $I_{OUT} = 15\text{mA}$, $V_L = 5.0$ V, $C_L = 10.5\text{pF}$ (see test circuit 6.)

Electrical Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	I _{OUT1}	5	$V_{OUT} = 0.4 \text{ V}, \text{ R-EXT} = 1.2 \text{ k}\Omega$ $V_{DD} = 3.3 \text{ V}, \text{ VG} = 1$		15		mA
Output current error between ICs	ΔI_{OUT1}	5	$\label{eq:VOUT} \begin{array}{l} V_{OUT} = 0.4 \ \text{V}, \ \text{R-EXT} = 1.2 \ \text{k}\Omega \\ \text{All channels ON} V_{DD} = 3.3 \ \text{V}, \\ \text{VG} = 1 \end{array}$		±3	±6	%
Output current error between channels	ΔI_{OUT2}	5	$\label{eq:VOUT} \begin{array}{l} V_{OUT} = 0.4 \text{ V}, \text{ R-EXT} = 1.2 \text{ k}\Omega \\ \text{All channels ON} \text{V}_{DD} = 3.3 \text{ V}, \\ \text{VG} = 1 \end{array}$	_	±1	±3	%
Output leakage current	I _{OZ}	5	$V_{OUT} = 25 V$	_	_	1	μA
laput veltage	VIH	_	SERIAL-IN/CLOCK/ TATCH /	$0.7 \times V_{DD}$	_	V _{DD}	V
Input voltage	VIL	_	SERIAL-IN/CLOCK/ TATCH /	GND	_	$0.3 \times V_{DD}$	v
	Iн	2	V _{IN} = VDD CLOCK/SERIAL-IN/ LATCH / ENABLE			1	
Input current	Ι _{ΙL}	3	V _{IN} = GND CLOCK/SERIAL-IN/ LATCH / ENABLE			-1	μA
SERIAL-OUT output voltage	V _{OL}	1	$I_{OL} = 5.0 \text{ mA}, V_{DD} = 3.3 \text{ V}$		_	0.3	V
	V _{OH}	1	I_{OH} = -5.0 mA, V_{DD} = 3.3 V	3.0	—	—	
OOD detection voltage	VOOD	7	5 to 40 mA	0.2	0.3	0.4	V
OSD detection voltage	V _{OSD}	7	5 to 40 mA	0.9 × V _{DD}	$0.95 \times V_{DD}$	V _{DD}	V
Changes in constant output current dependent on $V_{\mbox{\scriptsize DD}}$	%/V _{DD}	5	V _{DD} = 3 V to 5.5 V	_	1	2	%
Pull-up resistor	R _(Up)	3	ENABLE	160	200	240	kΩ
Pull-down resistor	R (Down)	2	LATCH	160	200	240	kΩ
	I _{DD} (OFF) 1	4	R-EXT = OPEN, V _{OUT} = 25.0 V	_	_	1	
Supply current	I _{DD (OFF) 2}	4	$\label{eq:result} \begin{array}{l} \text{R-EXT} = 1.2 \ \text{k}\Omega, \ \text{V}_{OUT} = 25.0 \ \text{V}, \\ \text{All channels OFF} \end{array}$	—	—	5	mA
	I _{DD (ON)}	4	R-EXT = 1.2 k Ω , V _{OUT} = 0.4 V, All channels ON	_	_	9	

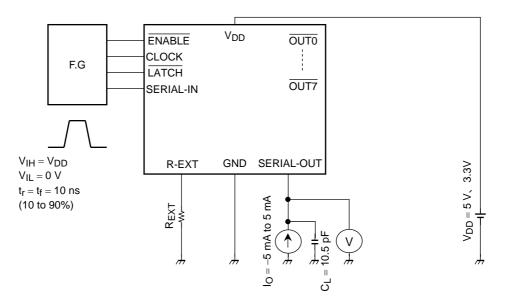
Switching Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	t _{pLH1}	6	$ \begin{array}{l} CLK- \overline{OUTn} \;, \;\; \overline{LATCH} = "H", \\ \overline{ENABLE} = "L" \end{array} $	_	_	300	
	t _{pLH2}	6	$\overline{\text{LATCH}} - \overline{\text{OUTn}},$ $\overline{\text{ENABLE}} = \text{``L''}$	_	_	300	
	t _{pLH3}	6	$\overline{\frac{ENABLE}{LATCH}} - \overline{OUTn} ,$	—	_	300	
Propagation delay time	t _{pLH}	6	CLK-SERIAL OUT	2	—	14	
n topagation delay time	^t pHL1	6	$ \begin{array}{l} CLK-\overline{OUTn} \ , \ \overline{LATCH} = "H", \\ \overline{ENABLE} = "L" \end{array} $	—	_	340	ns
	t _{pHL2}	6	$\overline{\text{LATCH}} - \overline{\text{OUTn}} ,$ $\overline{\text{ENABLE}} = \text{``L''}$	_	_	340	
	t _{pHL3}	6	ENABLE - OUTn , LATCH = "H"	_	_	340	
	^t pHL	6	CLK-SERIAL OUT	2	—	14	
Output rise time	t _{or}	6	10% to 90% points of OUT0 to OUT7 voltage waveforms	_	_	150	
Output fall time	t _{of}	6	00% to 10% points of \overline{OUTO}		_	300	

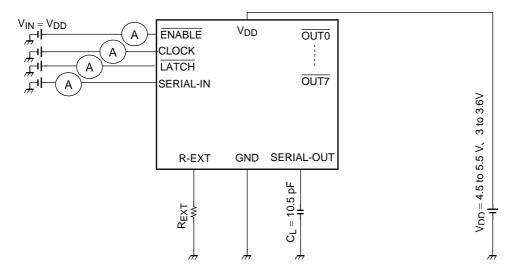
Note 1: $T_{opr} = 25^{\circ}C$, $V_{DD} = V_{IH} = 3.3$ V, $V_{IL} = 0$ V, $R_{EXT} = 1.2$ k Ω , $I_{OUT} = 15$ mA, $V_L = 5.0$ V, $C_L = 10.5$ pF (see test circuit 6.)

Test Circuits

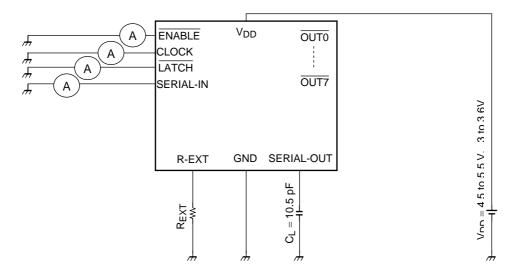
Test Circuit 1: High-Level and Low-Level Input Voltages (VIH/VIL)



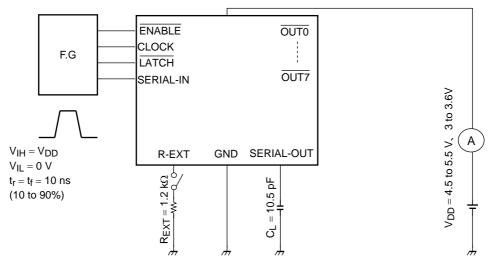
Test Circuit 2: High-Level Input Current (IIH)



Test Circuit 3: Low-Level Input Current (IIL)

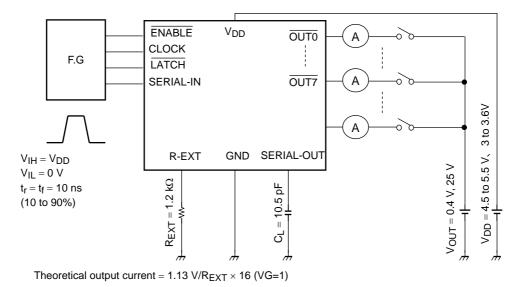


Test Circuit 4: Supply Current

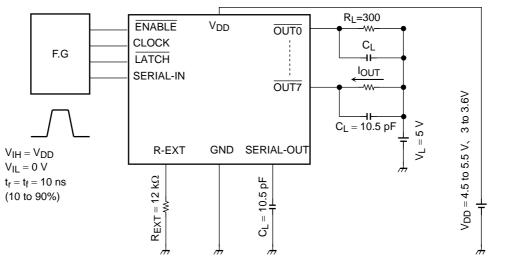


Note: The output terminal is based on the power supply current conditions on page 6 and 7.

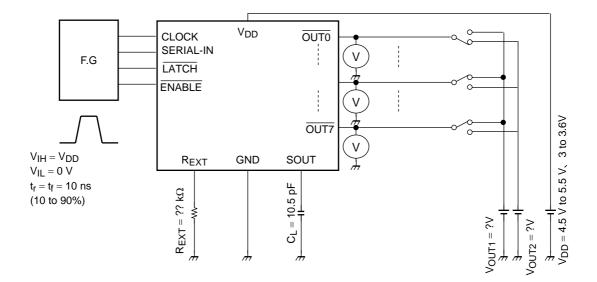
Test Circuit 5: Output Current (I_{OUT1}), Output Leakage Current (I_{OZ}) Output Current Variations ($\Delta I_{OUT1}/\Delta I_{OUT2}$), Current Variation with V_{DD} (%/V_{DD})



Test Circuit 6: Switching Characteristics

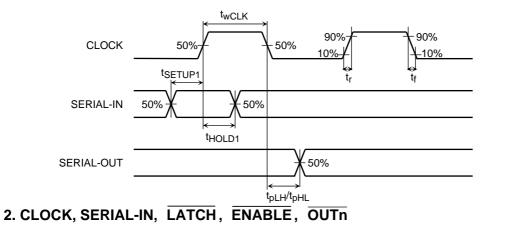


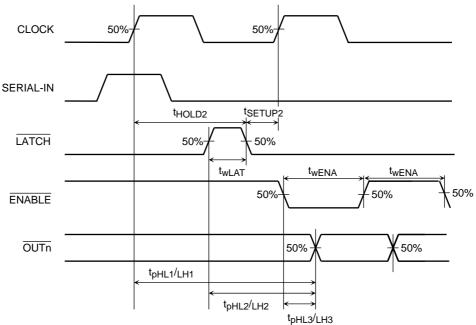
Test Circuit 7: ODD and OSD Characteristics



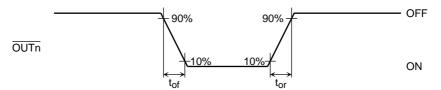
Timing Waveforms

1. CLOCK, SERIAL-IN, SERIAL-OUT

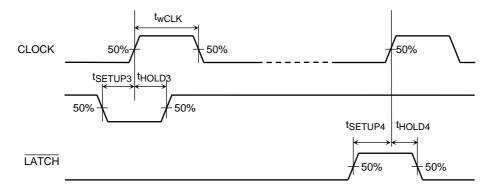




3. OUTn



4. Special Mode

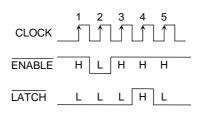


Note: The timing chart waveform may be simplified to explain a function and operation. Timing conditions must be taken care enough.

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Special Mode

Sequence for Switching to Special Mode

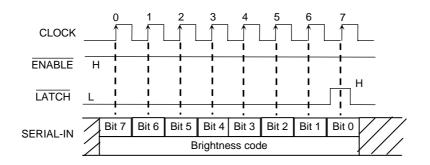


Only the above signal sequence puts the TB62778FNG in special mode. In this mode, two sub-modes are available: total brightness adjustment mode and error detection (OOD/OSD) mode.

While switching to special mode, data is not latched by \overline{LATCH} . After power-on, the TB62778FNG defaults to normal mode.

Total Brightness Adjustment Mode

Writing a brightness code



In total brightness adjustment mode, when \overrightarrow{LATCH} is High, a brightness code in the shift register is latched into the brightness adjustment register instead of the output latches. Once latched into the brightness adjustment register, the brightness code is held until the TB62778FNG is powered off or it is overwritten with a new code.

Adjusting the total brightness

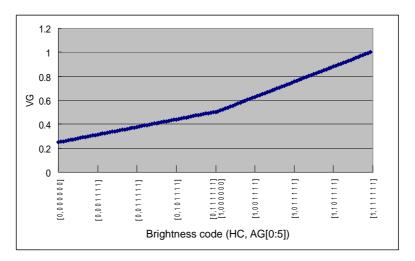
Bit definition of the brightness code

	Bit 0	Bit 1	Bit 2	Bit 3	Bit 4	Bit 5	Bit 6	Bit 7
	Reserved	HC	AG5	AG4	AG3	AG2	AG1	AG0
Default	1	1	1	1	1	1	1	1

The 8-bit brightness code is shifted in from the SERIAL-IN terminal, with bit 7 first. Bits 1 to 7 of the code determine the voltage applied to the R-EXT terminal (VG). Bit 1, HC, divides the voltage range into 25% to 50% (HC = 0) or 50% to 100% (HC = 1), and bits 2 to 7 are used to adjust the voltage in 64 steps within the range selected by bit 1. After on power, total brightness adjustment code becomes the above-mentioned default value.

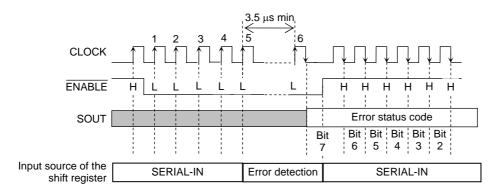
Theoretical Current Settings (preliminary)

 $Current = 1.13 V \times VG \div R\text{-}EXT \times 16$



Note) After setting up total luminance, it must be paid attention because the operation moves to the error detection mode (OOD) when five clocks are taken during the setting current output (\overline{ENABLE} = L period). (Please see the error detection mode on page 15.)

Error Detection Mode 1 (OOD Detection)

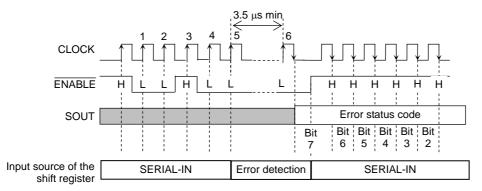


In special mode, the TB62778FNG not only enables the outputs but also performs error detection, and if any error is detected, loads an error status code into the shift register. For ODD detection, five Low bits must be shifted in. Immediately following the fifth Low bit, the input source of the shift register switches from the SERIAL-IN terminal to the 8-bit parallel error status code register. An error status code is generated at least 3.5µs from the fifth rising edge of CLOCK after ENABLE is set Low. If any Low bit occurs thereafter, the detected error status code is saved in the shift register. Therefore, while ENABLE is Low, serial data can not be shifted into the TB62778FNG via the SERIAL-IN terminal. Setting ENABLE high changes the input source of the shift register to the SERIAL-IN terminal, disables the outputs and terminates error detection. Thereupon, new serial data is shifted into the TB62778FNG via the SERIAL-IN terminal on the falling edge of CLOCK. The output is Hi-Z when the output is turning off before OOD detection. So please execute the OOD detection after the output is turning on.

Error Status Code in OOD Detection Mode

	Error Status Code	Output Terminal State
$V_{OOD} \geq V_{O}$	0	Open
$V_{OOD} < V_{O}$	1	Normal

Error Detection Mode 2 (OSD Detection)



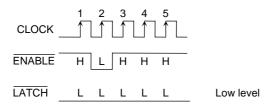
In special mode, the TB62778FNG not only enables the outputs but also performs error detection, and if any error is detected, loads an error status code into the shift register. For OSD detection, an L-L-H-L-L sequence must be shifted in. Immediately following the fifth Low bit, the input source of the shift register switches from the SERIAL-IN terminal to the 8-bit parallel error status code register. An error status code is generated at least 3.5 μ s from the fifth rising edge of CLOCK after ENABLE is set Low. If any Low bit occurs thereafter, the detected error status code is saved in the shift register. Therefore, while ENABLE is Low, serial data can not be shifted into the TB62778FNG via the SERIAL-IN terminal. Setting ENABLE high changes the input source of the shift register to the SERIAL-IN terminal, disables the outputs and terminates error detection. Thereupon, new serial data is shifted into the TB62778FNG via the SERIAL-IN terminal on the falling edge of CLOCK. TB62777FNG is over the power dissipation when OSD detection. So please execute the OSD detection after the output is turning off.

Error Status Code in OSD Detection Mode

	Error Status Code	Output Terminal State
$V_{OOD} \leq V_{O}$	0	Shorted
$V_{OOD} > V_{O}$	1	Normal

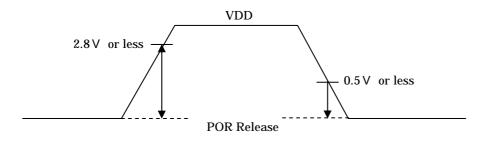
Note) The output current at the error detection mode is 25% of a set current (total brightness adjustment code (LSB) : minimum current setting).

Sequence for Switching to Normal Mode



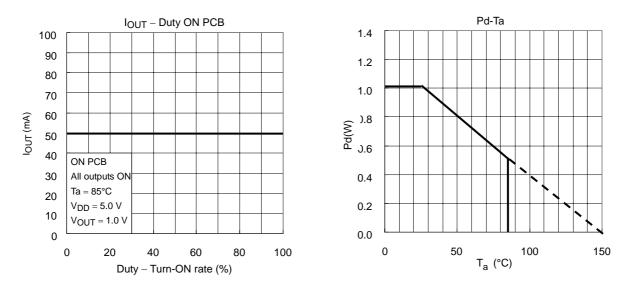
Only in the case of this signal sequence, it changes to the normal mode. Data is reset(0) when the mode is changes from the specified mode to the normal mode.

POR Characteristic

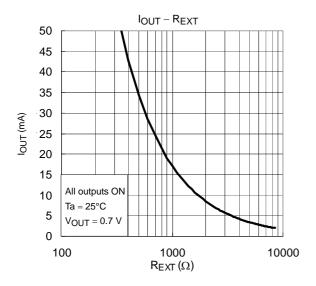


Output current vs. Dirating (lighting rate) graph

PCB Conditions: $76.2\times114.3\times1.6$ mm, Cu = 30%, 35-µm Thick, SEMI-Compliant



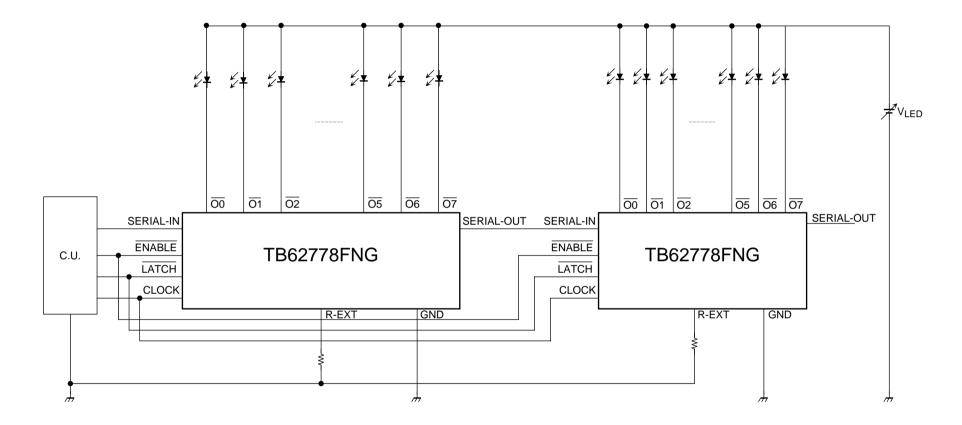
Output Current vs. External Resistor (typ.)



The above graphs are presented merely as a guide and does not constitute any guarantee as to the performance or characteristics of the device. Each product design should be fully evaluated in the real-world environment.

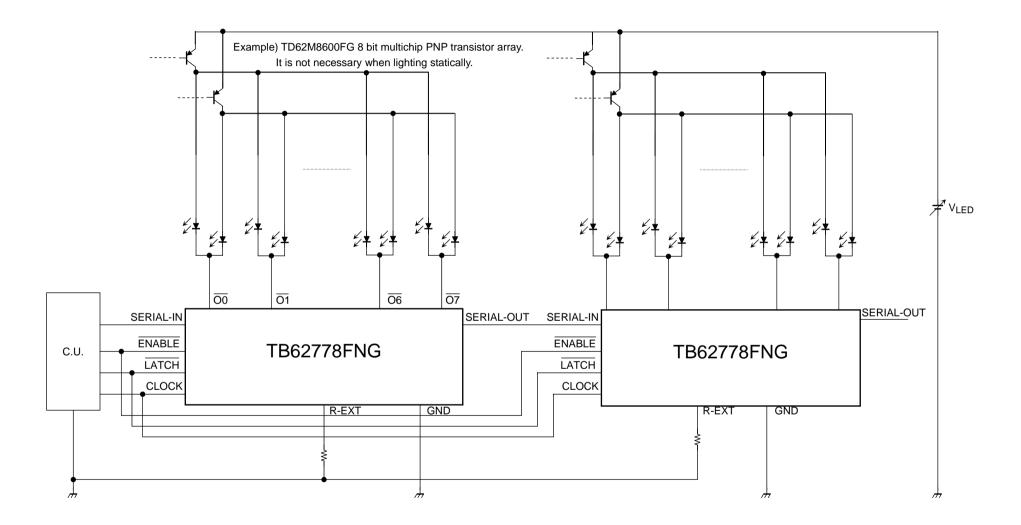
Application Circuit: General Composition for Dynamic Lighting of LEDs

In the following diagram, it is recommended that the LED supply voltage (V_{LED}) be equal to or greater than the sum of V_f (max) of all LEDs plus 0.7 V.

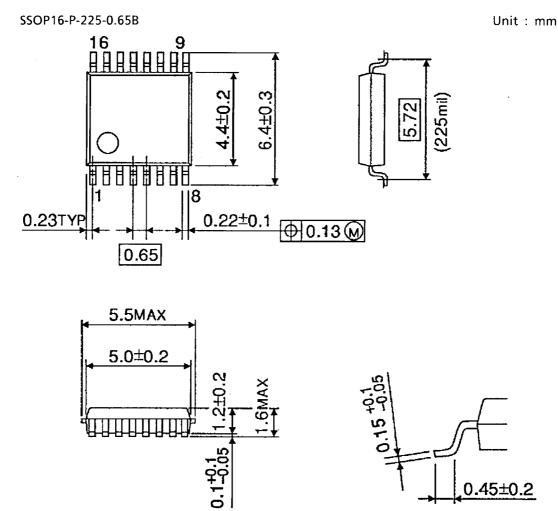


Application Circuit: General Composition for Dynamic Lighting of LEDs

In the following diagram, it is recommended that the LED supply voltage (VLED) be equal to or greater than the sum of V_f (max) of all LEDs plus 0.7 V.



Package Dimensions



Weight: 0.07 g (typ.)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage. Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on handling of ICs

- The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings. Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition. Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion. In addition, do not use any device that is applied the current with inserting in the wrong orientation or

In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

(5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator. If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

Points to remember on handling of ICs

(1) Over current Protection Circuit

Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately.

Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

(2) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

About solderability, following conditions were confirmed

Solderability

- (1) Use of Sn-37Pb solder Bath
 - solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - · use of R-type flux
- (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - solder bath temperature = 245°C
 - \cdot dipping time = 5 seconds
 - \cdot the number of times = once
 - use of R-type flux

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